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PATENT APPLICATION
Attorney Docket: 54364

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Gupta, et al.	
Serial No.:	09/847,667	
Filed:	5/1/2001	
For:	Method for Bonding Wafers to Produce Stacked Integrated Circuits	
Group Art Unit:	2827	Examiner: James Mitchell

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In reply to the Final Action dated 6/30/2004, in the above-identified patent application, Applicant submits the following Amendments and Remarks. Applicant respectfully requests that the following amendments be entered into the above-identified application and that the Examiner reconsider the grounds for rejection stated in the Final Action. This amendment is being submitted with a request for continuing examination. Since the Examiner did not enter the previously filed amendment, the claims shown below do not reflect any amendments in that response.